Product Bulletin

Document #:PB25486X1
Issue Date:16 May 2023

Title of Change:	Plastic casing change from POR case to MOD2 case
Effective date:	22 May 2023
Contact information:	Contact your local onsemi Sales Office or Way-Shan.Yong@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Assembly Change, Plastic casing change from POR case to MOD2 case
Change Sub-Category(s):	Material Change

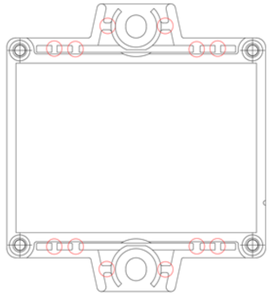
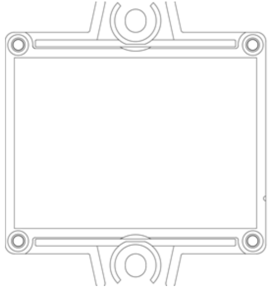
Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Shenzhen, China	None

Description and Purpose:

This PB announces the change of plastic case from POR case to MOD2 case. No change in case dimension.
PIM module production of F2 package is sourced from onsemi Shenzhen, China

Upon the issuance of this PB, affected F2 package modules will be produced with new plastic case. The product is qualified to industrial requirements.

Material to be changed	Before Change Description	After Change Description
Plastic case of F2	(POR case) 	(MOD2 case) 

"Changed material may be identified by date code".

List of Affected Standard Parts:

***Note**: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

NXH200B100H4F2SG	NXH200B100H4F2SG-R	